



100% Material Declaration Data Sheet for 7 Series CL484 Package

PK772 (v1.0) November 13, 2015

Average Weight: 1.1360 g

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Silicon Die					0.025878	2.278
	Silicon	7440-21-3	100.00		0.025878	
Die Attach Material					0.008105	0.713
	Silver	7440-22-4	77.50		0.006281	
	Bismaleimide monomer	Trade Secret	15.00		0.001216	
	Acrylate monomer	Trade Secret	7.50		0.000608	
Mold Compound					0.476919	41.981
	Epoxy Resin	Trade secret	5.00		0.023846	
	Phenol Resin	Trade secret	3.00		0.014308	
	Phenol Novolac	9003-35-4	3.00		0.014308	
	Metal Hydroxide	Trade Secret	3.00		0.014308	
	Carbon black	1333-86-4	0.30		0.001431	
	Silica fused	60676-86-0	70.40		0.335751	
	Silica Dioxide	7631-86-9	15.00		0.071538	
Silica, crystalline	14808-60-7	0.30		0.001431		
Copper Wire					0.006315	0.556
	Copper	7440-50-8	98.20		0.006201	
	Palladium	7440-05-3	1.80		0.000114	
Solder Ball					0.233980	20.596
	Tin	7440-31-5	63.00		0.147407	
	Lead	7439-92-1	37.00		0.086573	
Substrate					0.384804	33.872
	Gold	7440-57-5	0.21		0.000808	
	Nickel	7440-02-0	1.22		0.004695	
	Copper	7440-50-8	44.30		0.170468	
	Glass Fiber	65997-17-3	21.20		0.081578	
	Non halogen fire retardant	Trade Secret	0.01		0.000038	
	BT Core	105391-33-1/ 25722-66-1/ Trade Secret	25.91		0.099703	
Solder Mask	34590-94-8/ 7727-43-7/ Trade Secret	7.17		0.027590		

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Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
11/13/2015	1.0	Xilinx Initial Release

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